

REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	Update boilerplate paragraphs to current requirements. - PHN	09-05-27	Thomas M. Hess
B	Update boilerplate to current MIL-PRF-38535 requirements. - PHN	15-09-28	Thomas M. Hess



CURRENT DESIGN ACTIVITY CAGE CODE 16236
 HAS CHANGED NAMES TO:
 DLA LAND AND MARITIME
 COLUMBUS, OHIO 43218-3990

Prepared in accordance with ASME Y14.24

Vendor item drawing

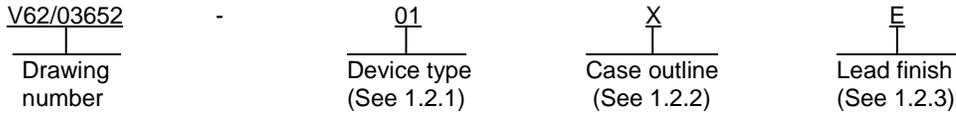
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REV STATUS OF PAGES	REV	B	B	B	B	B	B	B	B	B	B	B	B	B						
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PMIC N/A	PREPARED BY Charles F. Saffle	DEFENSE SUPPLY CENTER, COLUMBUS COLUMBUS, OHIO 43218-3990	
Original date of drawing YY-MM-DD 03-08-19	CHECKED BY Charles F. Saffle	TITLE MICROCIRCUIT, DIGITAL, ADVANCED HIGH SPEED CMOS, DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET, MONOLITHIC SILICON	
	APPROVED BY Thomas M. Hess		
	SIZE A	CODE IDENT. NO. 16236	DWG NO. V62/03652
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1. SCOPE

1.1 Scope. This drawing documents the general requirements of a high performance dual positive-edge-triggered D-type flip-flop with clear and preset microcircuit, with an operating temperature range of -55°C to +125°C.

1.2 Vendor Item Drawing Administrative Control Number. The manufacturer's PIN is the item of identification. The vendor item drawing establishes an administrative control number for identifying the item on the engineering documentation:



1.2.1 Device type(s).

<u>Device type</u>	<u>Generic</u>	<u>Circuit function</u>
01	74AHC74-EP	Dual positive-edge-triggered D-type flip-flop with clear and preset

1.2.2 Case outlines. The case outlines are as specified herein.

<u>Outline letter</u>	<u>Number of pins</u>	<u>JEDEC PUB 95</u>	<u>Package style</u>
X	14	JEDEC MO-153	Plastic small-outline
Y	14	JEDEC MS-012	Plastic small-outline

1.2.3 Lead finishes. The lead finishes are as specified below or other lead finishes as provided by the device manufacturer:

<u>Finish designator</u>	<u>Material</u>
A	Hot solder dip
B	Tin-lead plate
C	Gold plate
D	Palladium
E	Gold flash palladium
Z	Other

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1.3 Absolute maximum ratings. 1/

Supply voltage range (V_{CC})	-0.5 V to +7.0 V
Input voltage range (V_i)	-0.5 V to +7.0 V 2/
Output voltage range (V_o)	-0.5 V to $V_{CC} + 0.5$ V 2/
Input clamp current (I_{IK}) ($V_i < 0$)	-20 mA
Output clamp current (I_{OK}) ($V_o < 0$ or $V_o > V_{CC}$)	± 20 mA
Continuous output current (I_o) ($V_o = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance (θ_{JA}):	
X package	113°C/W 3/
Y package	86°C/W 3/
Storage temperature range (T_{STG})	-65°C to +150°C

1.4 Recommended operating conditions. 4/ 5/

Supply voltage range (V_{CC})	2.0 V to 5.5 V
Minimum high level input voltage (V_{IH}):	
$V_{CC} = 2.0$ V	1.5 V
$V_{CC} = 3.0$ V	2.1 V
$V_{CC} = 5.5$ V	3.85 V
Maximum low level input voltage (V_{IL}):	
$V_{CC} = 2.0$ V	0.5 V
$V_{CC} = 3.0$ V	0.9 V
$V_{CC} = 5.5$ V	1.65 V
Input voltage range (V_i)	0.0 V to 5.5 V
Output voltage range (V_o)	0.0 V to V_{CC}
Maximum high level output current (I_{OH}):	
$V_{CC} = 2.0$ V	-50 μ A
$V_{CC} = 3.3$ V ± 0.3 V	-4.0 mA
$V_{CC} = 5.0$ V ± 0.5 V	-8.0 mA
Maximum low level output current (I_{OL}):	
$V_{CC} = 2.0$ V	50 μ A
$V_{CC} = 3.3$ V ± 0.3 V	4.0 mA
$V_{CC} = 5.0$ V ± 0.5 V	8.0 mA
Maximum input transition rise or fall rate ($\Delta t/\Delta v$):	
$V_{CC} = 3.3$ V ± 0.3 V	100 ns/V
$V_{CC} = 5.0$ V ± 0.5 V	20 ns/V
Operating free-air temperature range (T_A)	-55°C to +125°C

- 1/ Stresses beyond those listed under “absolute maximum rating” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2/ The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- 3/ The package thermal impedance is calculated in accordance with JESD 51-7.
- 4/ Use of this product beyond the manufacturers design rules or stated parameters is done at the user’s risk. The manufacturer and/or distributor maintain no responsibility or liability for product used beyond the stated limits.
- 5/ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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2. APPLICABLE DOCUMENTS

JEDEC – SOLID STATE TECHNOLOGY ASSOCIATION (JEDEC)

- JEP95 – Registered and Standard Outlines for Semiconductor Devices
- JESD51-7 – High Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages

(Copies of these documents are available online at <http://www.jedec.org> or from JEDEC – Solid State Technology Association, 3103 North 10th Street, Suite 240–S, Arlington, VA 22201-2107).

3. REQUIREMENTS

3.1 Marking. Parts shall be permanently and legibly marked with the manufacturer’s part number as shown in 6.3 herein and as follows:

- A. Manufacturer’s name, CAGE code, or logo
- B. Pin 1 identifier
- C. ESDS identification (optional)

3.2 Unit container. The unit container shall be marked with the manufacturer’s part number and with items A and C (if applicable) above.

3.3 Electrical characteristics. The maximum and recommended operating conditions and electrical performance characteristics are as specified in 1.3, 1.4, and table I herein.

3.4 Design, construction, and physical dimension. The design, construction, and physical dimensions are as specified herein.

3.5 Diagrams.

3.5.1 Case outlines. The case outlines shall be as shown in 1.2.2 and figure 1.

3.5.2 Truth table. The truth table shall be as shown in figure 2.

3.5.3 Logic diagram. The logic diagram shall be as shown in figure 3.

3.5.4 Terminal connections. The terminal connections shall be as shown in figure 4.

3.5.5 Timing waveforms and test circuit. The timing waveforms and test circuit shall be as shown in figure 5.

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TABLE I. Electrical performance characteristics. 1/

Test	Symbol	Conditions	V _{CC}	Temperature, T _A	Device type	Limits		Unit
						Min	Max	
High level output voltage	V _{OH}	I _{OH} = -50 μA	2.0 V	25°C, -55°C to 125°C	01	1.9		V
			3.0 V			2.9		
			4.5 V			4.4		
		I _{OH} = -4 mA	3.0 V	25°C		2.58		
				-55°C to 125°C		2.48		
		I _{OH} = -8 mA	4.5 V	25°C		3.94		
		-55°C to 125°C	3.80					
Low level output voltage	V _{OL}	I _{OL} = 50 μA	2.0 V	25°C, -55°C to 125°C	01		0.1	V
			3.0 V				0.1	
			4.5 V				0.1	
		I _{OL} = 4 mA	3.0 V	25°C			0.36	
				-55°C to 125°C			0.5	
		I _{OL} = 8 mA	4.5 V	25°C			0.36	
		-55°C to 125°C		0.5				
Input current, A or B inputs	I _I	V _I = 5.5 V or GND	0.0 V to 5.5 V	25°C	01		±0.1	μA
				-55°C to 125°C			±1.0	
Quiescent supply current	I _{CC}	V _I = V _{CC} or GND I _O = 0 A	5.5 V	25°C	01		2.0	μA
				-55°C to 125°C			20.0	
Input capacitance	C _I	V _I = V _{CC} or GND	5.0 V	25°C	01		10	pF
Power dissipation capacitance	C _{pd}	No load f = 1 MHz	5.0 V	25°C	01	32 TYP		pF
Quiet output, maximum dynamic V _{OL}	V _{OL(P)} 2/	C _L = 50 pF	5.0 V	25°C	01		0.8	V
Quiet output, minimum dynamic V _{OL}	V _{OL(V)} 2/		5.0 V	25°C	01		-0.8	V
Quiet output, minimum dynamic V _{OH}	V _{OH(V)} 2/		5.0 V	25°C	01	4.7		V
High level dynamic input voltage	V _{IH(D)} 2/		5.0 V	25°C	01	3.5		V
Low level dynamic input voltage	V _{IL(D)} 2/		5.0 V	25°C	01		1.5	V

See footnote at end of table.

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TABLE I. Electrical performance characteristics - Continued. 1/

Test	Symbol	Conditions	V _{CC}	Temperature, T _A	Device type	Limits		Unit
						Min	Max	
Maximum clock frequency	f _{max}	C _L = 15 pF	3.0 V and 3.6 V	25°C	01	80		MHz
				-55°C to 125°C		70		
			4.5 V and 5.5 V	25°C		130		
				-55°C to 125°C		110		
		C _L = 50 pF	3.0 V and 3.6 V	25°C		50		
				-55°C to 125°C		45		
			4.5 V and 5.5 V	25°C		90		
				-55°C to 125°C		75		
Propagation delay time, $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ to Q or $\overline{\text{Q}}$	t _{PLH} , t _{PHL}	C _L = 15 pF See figure 5	3.0 V and 3.6 V	25°C	01		12.3	ns
				-55°C to 125°C		1.0	14.5	
			4.5 V and 5.5 V	25°C			7.7	
				-55°C to 125°C		1.0	9.0	
		C _L = 50 pF See figure 5	3.0 V and 3.6 V	25°C			15.8	
				-55°C to 125°C		1.0	18.0	
			4.5 V and 5.5 V	25°C			9.7	
				-55°C to 125°C		1.0	11.0	
Propagation delay time, CLK to Q or $\overline{\text{Q}}$	t _{PLH} , t _{PHL}	C _L = 15 pF See figure 5	3.0 V and 3.6 V	25°C	01		11.9	ns
				-55°C to 125°C		1.0	14.0	
			4.5 V and 5.5 V	25°C			7.3	
				-55°C to 125°C		1.0	8.5	
		C _L = 50 pF See figure 5	3.0 V and 3.6 V	25°C			15.4	
				-55°C to 125°C		1.0	17.5	
			4.5 V and 5.5 V	25°C			9.3	
				-55°C to 125°C		1.0	10.5	

See footnote at end of table.

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TABLE I. Electrical performance characteristics - Continued. 1/

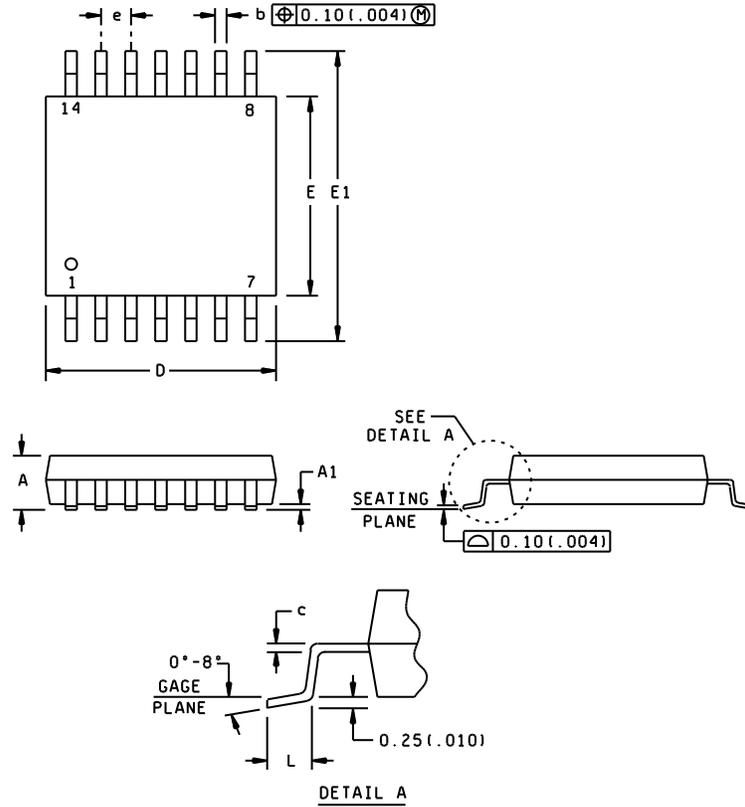
Test	Symbol	Conditions	V _{CC}	Temperature, T _A	Device type	Limits		Unit
						Min	Max	
Pulse duration	t _w	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low See figure 5	3.0 V and 3.6 V	25°C	01	6.0		ns
				-55°C to 125°C		7.0		
			4.5 V and 5.5 V	25°C		5.0		
				-55°C to 125°C		5.0		
		CLK See figure 5	3.0 V and 3.6 V	25°C		6.0		
				-55°C to 125°C		7.0		
			4.5 V and 5.5 V	25°C		5.0		
				-55°C to 125°C		5.0		
Setup time before CLK↑	t _{su}	Data See figure 5	3.0 V and 3.6 V	25°C	01	6.0		ns
				-55°C to 125°C		7.0		
			4.5 V and 5.5 V	25°C		5.0		
				-55°C to 125°C		5.0		
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive See figure 5	3.0 V and 3.6 V	25°C		5.0		
				-55°C to 125°C		5.0		
			4.5 V and 5.5 V	25°C		3.0		
				-55°C to 125°C		3.0		
Hold time, data after CLK↑	t _h	See figure 5	3.0 V and 3.6 V	25°C	01	0.5		ns
				-55°C to 125°C		0.5		
			4.5 V and 5.5 V	25°C		0.5		
				-55°C to 125°C		0.5		

1/ Testing and other quality control techniques are used to the extent deemed necessary to assure product performance over the specified temperature range. Product may not necessarily be tested across the full temperature range and all parameters may not necessarily be tested. In the absence of specific parametric testing, product performance is assured by characterization and/or design.

2/ Characteristics are for surface-mount packages only.

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Case X



Dimensions									
Symbol	Millimeters		Inches		Symbol	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	---	1.20	---	.047	E	4.30	4.50	.169	.177
A1	0.05	0.15	.002	.006	E1	6.20	6.60	.244	.260
b	0.19	0.30	.007	.012	e	0.65 NOM		.026 NOM	
c	0.15 NOM		.006 NOM		L	0.50	0.75	.020	.030
D	4.90	5.10	.193	.201					

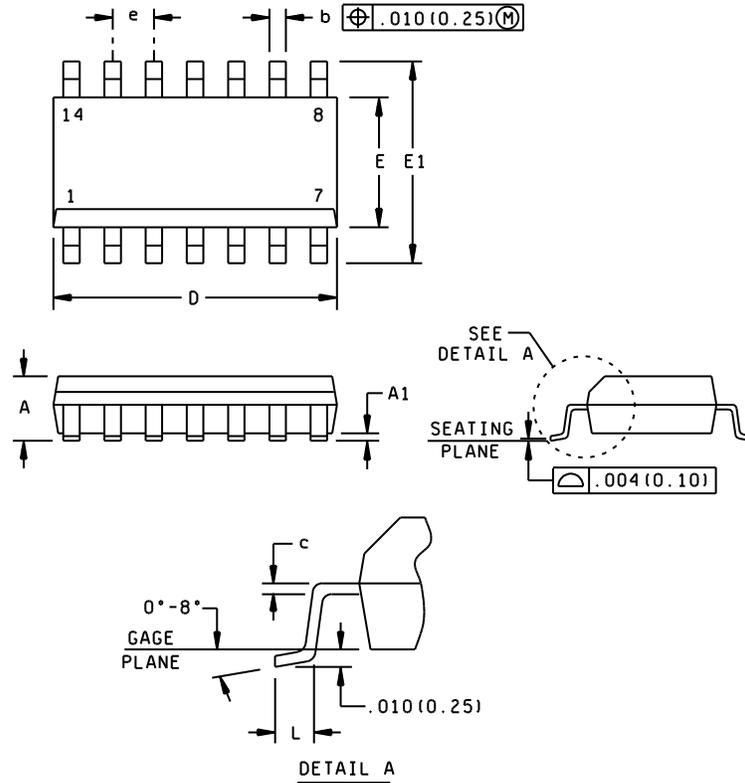
NOTES:

1. This drawing is subject to change without notice.
2. Body dimensions do not include mold flash or protrusion not to exceed 0.15 mm.
3. Falls within JEDEC MO-153.
4. All linear dimensions are shown in millimeters (inches). Inches equivalents are given for general information only.

FIGURE 1. Case outlines.

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Case Y



Dimensions									
Symbol	Millimeters		Inches		Symbol	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	---	1.75	---	.069	E	3.81	4.00	.150	.157
A1	0.10	0.25	.004	.010	E1	5.80	6.20	.228	.244
b	0.35	0.51	.014	.020	e	1.27 NOM		.050 NOM	
c	0.20 NOM		.008 NOM		L	0.40	1.12	.016	.044
D	8.55	8.75	.337	.344					

NOTES:

1. This drawing is subject to change without notice.
2. Body dimensions do not include mold flash or protrusion not to exceed 0.006 inches (0.15 mm).
3. Falls within JEDEC MS-012.
4. All linear dimensions are shown in inches (millimeters). Metric equivalents are given for general information only.

FIGURE 1. Case outlines - Continued.

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(each flip-flop)

Inputs				Outputs	
$\overline{\text{PRE}}$	$\overline{\text{CLR}}$	CLK	D	Q	$\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H*	H*
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	\overline{Q}_0

X = Immaterial

↑ = Rising edge of CLK

* = This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

FIGURE 2. Truth table.

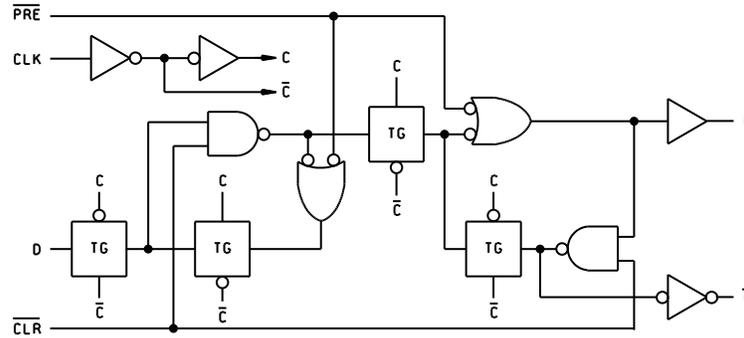
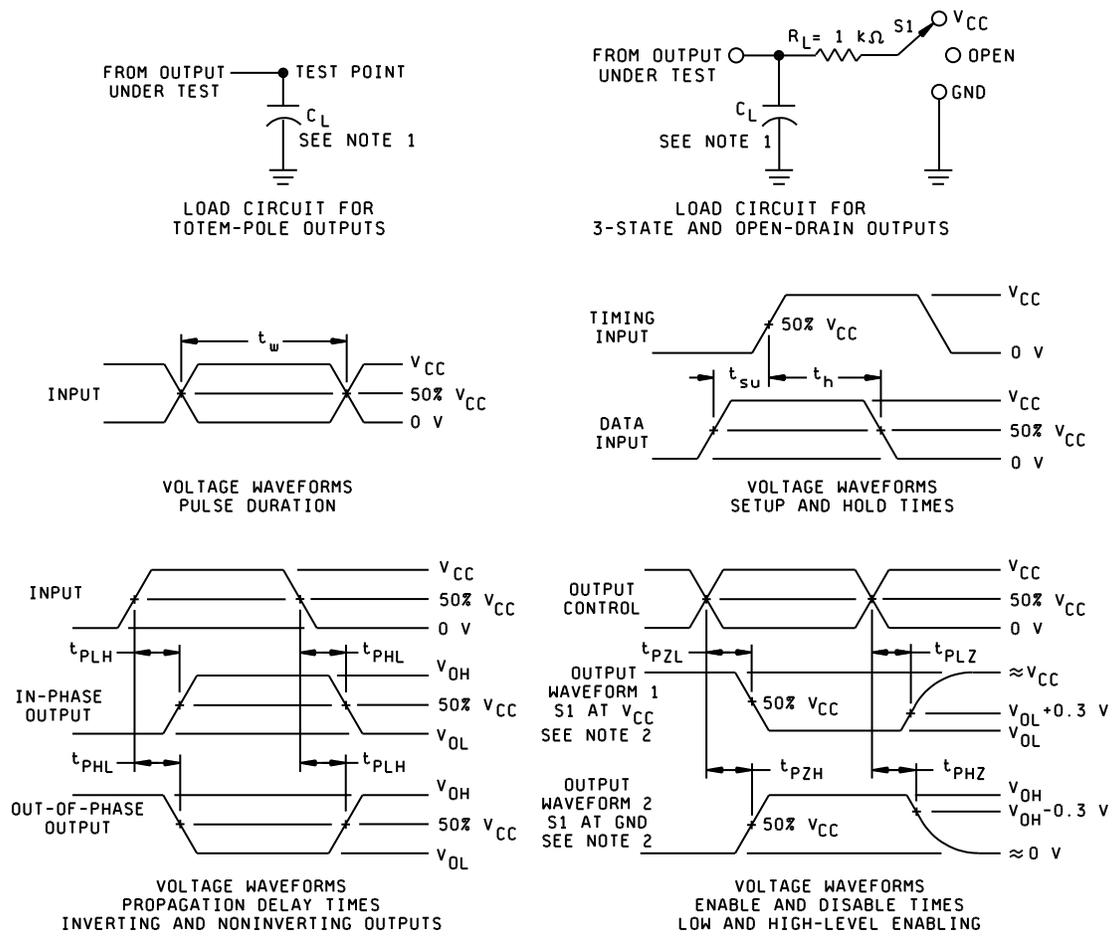


FIGURE 3. Logic diagram.

Device type 01			
Case outlines: X and Y			
Terminal number	Terminal symbol	Terminal number	Terminal symbol
1	1 CLR	8	2 $\overline{\text{Q}}$
2	1 D	9	2 Q
3	1 CLK	10	2 $\overline{\text{PRE}}$
4	1 $\overline{\text{PRE}}$	11	2 CLK
5	1 Q	12	2 D
6	1 $\overline{\text{Q}}$	13	2 $\overline{\text{CLR}}$
7	GND	14	V_{CC}

FIGURE 4. Terminal connections.

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Notes:

1. C_L includes probe and jig capacitance.
2. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
3. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_0 = 50\Omega$, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$.
4. The outputs are measured one at a time with one input transition per measurement.
5. For 3-state and Open Drain outputs tests:

t_{PLH}/t_{PHL}	$S1 = \text{Open}$
t_{PLZ}/t_{PZL}	$S1 = V_{CC}$
t_{PHZ}/t_{PZH}	$S1 = \text{GND}$
Open Drain	$S1 = V_{CC}$

FIGURE 5. Timing waveforms and test circuit.

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4. VERIFICATION

4.1 Product assurance requirements. The manufacturer is responsible for performing all inspection and test requirements as indicated in their internal documentation. Such procedures should include proper handling of electrostatic sensitive devices, classification, packaging, and labeling of moisture sensitive devices, as applicable.

5. PREPARATION FOR DELIVERY

5.1 Packaging. Preservation, packaging, labeling, and marking shall be in accordance with the manufacturer's standard commercial practices for electrostatic discharge sensitive devices.

6. NOTES

6.1 ESDS. Devices are electrostatic discharge sensitive and are classified as ESDS class 1 minimum.

6.2 Configuration control. The data contained herein is based on the salient characteristics of the device manufacturer's data book. The device manufacturer reserves the right to make changes without notice. This drawing will be modified as changes are provided.

6.3 Suggested source(s) of supply. Identification of the suggested source(s) of supply herein is not to be construed as a guarantee of present or continued availability as a source of supply for the item. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.landandmaritime.dla.mil/Programs/Smcr/>.

Vendor item drawing administrative control number ^{1/}	Device manufacturer CAGE code	Vendor part number	Top-Side Marking
V62/03652-01XE	01295	SN74AHC74MPWREP	AHC74EP
V62/03652-01YE	01295	SN74AHC74MDREP	AHC74MEP

^{1/} The vendor item drawing establishes an administrative control number for identifying the item on the engineering documentation.

CAGE code

01295

Source of supply

Texas Instruments, Inc.
 Semiconductor Group
 8505 Forest lane
 P.O. Box 660199
 Dallas, TX 75243
 Point of contact: U.S. Highway 75 South
 P.O. Box 84, M/S 853
 Sherman, TX 75090-9493

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